Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-10-28
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STL225N6F7AG	BXY5*OD68Q72	A	SH1A	2016-10-28
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	100.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	6, 5, 1	8	pin	
Comment	Package: PowerFLAT 5x6 WF			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	**true**
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false

Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						**Mfr Item Name**	**BXY5*OD68Q72**					
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die	Other inorganic materials	2.919	mg	supplier	die	Silicon (Si)	7440-21-3		2.483	mg	850634	24830
				supplier	metallization	Aluminium (Al)	7429-90-5		0.164	mg	56184	1640
				supplier	metallization	Titanium (Ti)	7440-32-6		0.018	mg	6166	180
				supplier	metallization	Tungsten (W)	7440-33-7		0.041	mg	14046	410
				supplier	metallization	Nickel (Ni)	7440-02-0		0.041	mg	14046	410
				supplier	metallization	Silver (Ag)	7440-22-4		0.024	mg	8222	240
				supplier	Passivation	Silicon Nitride	12033-89-5		0.017	mg	5824	170
				supplier	Passivation	Silicon Oxide	7631-86-9		0.040	mg	13703	400
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.005	mg	1713	50
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.058	mg	19870	580
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.004	mg	1370	40
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.024	mg	8222	240
Leadframe	Copper & its alloys	42.645	mg	supplier	alloy	Copper (Cu)	7440-50-8		40.580	mg	951577	405800
				supplier	alloy	Iron (Fe)	7439-89-6		0.954	mg	22371	9540
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.057	mg	1337	570
				supplier	alloy	Zinc (Zn)	7440-66-6		0.050	mg	1172	500
				supplier	metallization	Silver (Ag)	7440-22-4		1.004	mg	23543	10040
Soft solder	Solder	4.238	mg	JIG-R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.047	mg	954932	40470
				supplier	solder	Silver (Ag)	7440-22-4		0.106	mg	25011	1060
				supplier	solder	Tin (Sn)	7440-31-5		0.085	mg	20057	850
Bonding wire & Clip	Precious metals	8.029	mg	supplier	wire	Gold (Au)	7440-57-5		0.174	mg	21671	1740
				supplier	clip	Copper (Cu)	7440-50-8		7.855	mg	978329	78550
Encapsulation	Other inorganic materials	42.012	mg	supplier	mold compound	Silica, vitreous	60676-86-0		32.981	mg	785038	329810
				supplier	mold compound	epoxy resin	25068-38-6		5.461	mg	129987	54610
				supplier	mold compound	phenol resin	9003-35-4		2.520	mg	59983	25200
				supplier	mold compound	metal hydroxide	21645-51-2		0.840	mg	19993	8400
				supplier	mold compound	Carbon black	1333-86-4		0.210	mg	4999	2100
Connections coating	Solder	0.157	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.157	mg	1000000	1570